Panasonic

Zener Diode DZ2715000L

DZ2715000L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit DZ2S150 in SSSMini2 type package

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: UJ

Packaging

Embossed type (Thermo-compression sealing) 10 000 pcs / reel (standard)

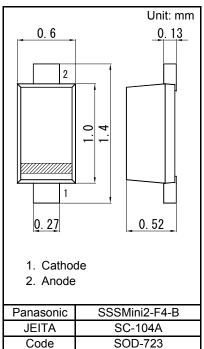
■ Absolute Maximum Ratings Ta = 25 °C

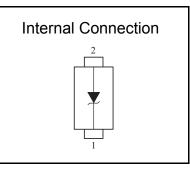
Parameter	Symbol	Rating	Unit	
Repetitive peak forward current	IFRM	200	mA	
Total power dissipation ^{*1}	PT	120	mW	
Electrostatic discharge *2	ESD	±8	kV	
Junction temperature	Tj	150	°C	
Operating ambient temperature	Topr	-40 to +85	°C	
Storage temperature	Tstg	-55 to +150	°C	

 Storage temperature
 Tstg
 -55 to
 +150
 °(

 Note)
 *1: Mounted on glass epoxy print board. (45 mm x 45 mm x 1 mm) Solder in (0.4 mm x 0.3 mm)
 Solder in (0.4 mm x 0.3 mm)

*2: Test method:IEC61000_4_2(C = 150 pF,R = 330 Ω, Contact discharge:10 times)





■ Electrical Characteristics Ta = 25 °C ± 3 °C							
Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Forward voltage	VF	IF = 10 mA			1.0	V	
Zener voltage *1, *2	VZ	IZ = 5 mA	14.25		15.60	V	
Zener operating resistance	RZ	IZ = 5 mA			40	Ω	
Zener rise operating resistance	RZK	IZ = 0.5 mA			80	Ω	
Reverse current	IR	VR = 11 V			0.05	μA	
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		13.4		mV/°C	

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25 °C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25°C)

*2 VZ guaranted 20 ms after current flow.

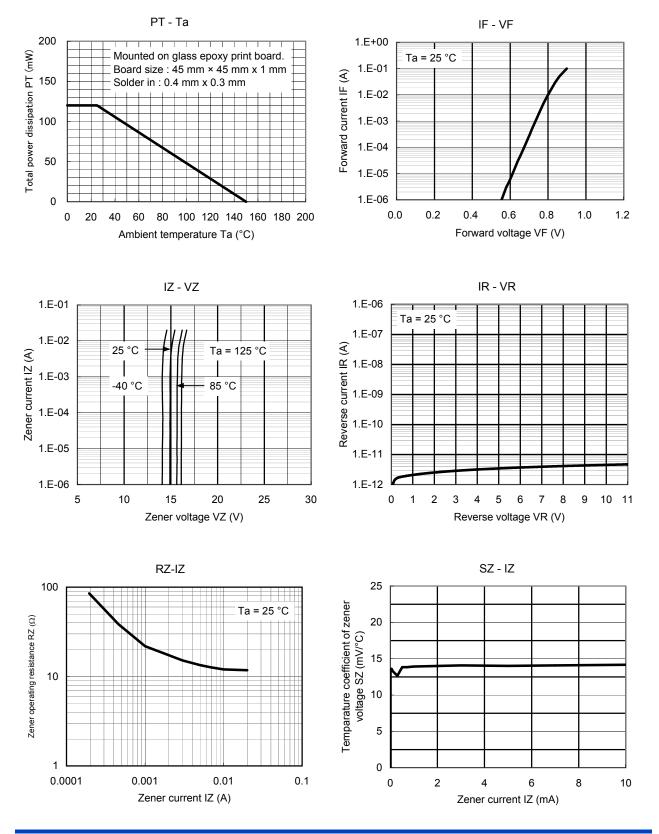
*3 Tj = 25 °C to 150 °C





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Technical Data (reference)

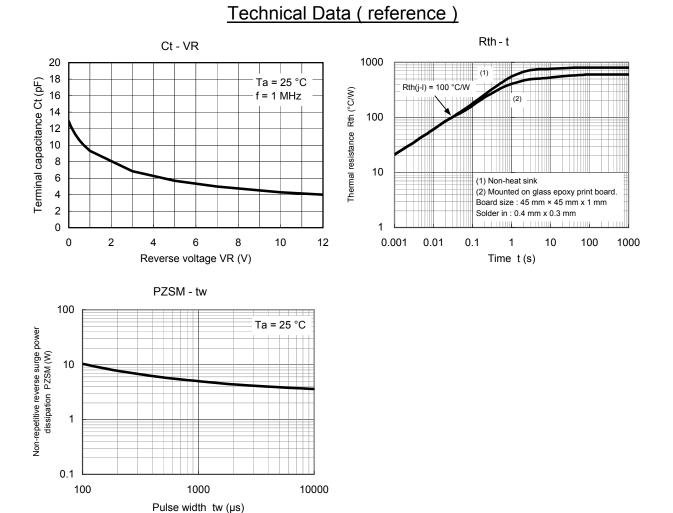


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Established : 2011-04-28 Revised : 2013-10-16



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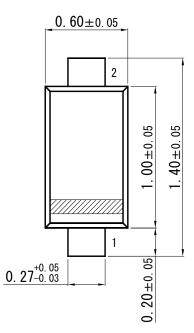
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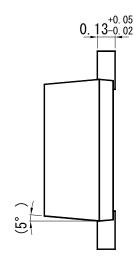
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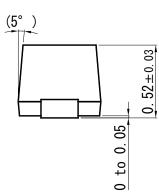


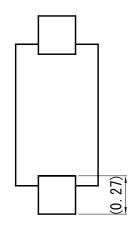
Zener Diode DZ2715000L

SSSMini2-F4-B

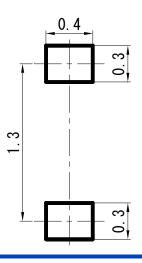








Land Pattern (Reference) (Unit: mm)



Established : 2011-04-28 Revised : 2013-10-16 Unit: mm

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